

REMARKS/ARGUMENTS

Favorable reconsideration of this application, in light of the present amendments and following discussion, is respectfully requested.

Claims 1-7 are pending. By this amendment Claims 1, 5 and 7 are amended.

Applicants appreciate the courtesies extended to Applicants' representative during the January 19th personal interview. The substance of the discussions held are incorporated into amendments and the following remarks and constitute Applicants' record of the interview.

In the outstanding Office Action, Claims 1-7 were rejected under 35 U.S.C. § 103(a) by USP 6,634,564 to Kuramochi in view of USP 6,601,770 to Ikefuji et al. This rejection is respectfully traversed.

Before considering the rejection under 35 U.S.C. § 103, it is believed that a brief review of the subject matter of the independent claims would be helpful. Independent Claim 1 includes a method for making an IC card including forming antenna leads and connection leads on an antenna substrate having a first side and a second side, mounting an IC chip on the first side of the antenna substrate such that the IC chip is electrically connected to the antenna substrate via the antenna leads and the connection leads, mounting an external electrode chip having an external electrode on the first side of the antenna substrate such that the external electrode chip is electrically connected to the antenna substrate via the connection leads, disposing a sheath having a hole on the antenna substrate and the external electrode chip is disposed in the hole and the external electrode is exposed at the surface of the sheet.

Claim 5 includes, *inter alia*, an IC card including an antenna substrate having patterned antenna leads and connection leads for non-contact communication, the antenna substrate having first and second surfaces, a first sheath layer disposed above the first surface of the antenna substrate, the first sheath layer having a hole, an external electrode chip

mounted in the hole on the first surface of the antenna substrate, the external electrode chip having an external electrode exposed at the surface of the first sheath layer and an IC chip electrically connected to the antenna substrate and the external electrode via the connections leads, the IC chip mounted on the first surface of the antenna substrate.

With respect to amended independent Claims 1 and 5, neither Kuramochi nor Ikefiji disclose the external electrode chip and the IC chip mounted on the first surface of the antenna substrate. Instead, Kuramochi discloses that the semiconductor chip 110 is mounted on the first major surface 120a of base member 120 and terminals 131 and 132 are attached to the second major surface 102b of the base member 120. As discussed in Kuramochi at column 2, lines 62 et seq. it is preferable that the semiconductor chip is disposed on a first major surface and the contact terminal is formed on a second major surface.

Ikefiji does not cure the deficiencies of Kuramochi. Contact terminal 24 is mounted on one surface of the circuit board 22 and IC chip 82 is mounted on the other surface of the circuit board 22. Furthermore, contact terminal 24 is located on one surface of the core member and IC chip 82 is located in the interior of the core member 30.

The dependent claims are allowable for at least the reasons discussed above and for the individual features they recite. Withdrawal of the rejections of the dependent claims is respectfully requested.

For the foregoing reasons, it is respectfully submitted that this application is now in condition for allowance. A Notice of Allowance is earnestly solicited.

Should the Examiner deem that any further action is necessary to place this application in even better form for allowance, the Examiner is encouraged to contact Applicants' undersigned representative at the telephone number listed below.

Respectfully submitted,

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